

ABSTRACT

BOND HEADS FOR THERMOCOMPRESSSION BONDERS, THERMOCOMPRESSSION BONDERS, AND METHODS OF OPERATING THE SAME

A bond head for a thermocompression bonder is provided. The bond head includes a tool configured to hold a workpiece to be bonded, a heater configured to heat the workpiece to be bonded, and a chamber proximate the heater. The chamber is configured to receive a cooling fluid for cooling the heater.

Figs. 5A-5B